

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: James C Matayabas et al.

Title: POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION

Docket No.: 884.946US1
Filed: June 30, 2003
Examiner: Howard Weiss

Serial No.: 10/612,328
Due Date: April 30, 2005
Group Art Unit: 2814

MS AF

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response under 37 CFR 1.116 (6 Pages).

Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

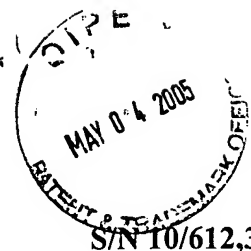
By: J M Kalis
Atty: Janal M. Kalis
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 29th day of April, 2005.

Amy Moriarty
Name

[Signature]
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)



EXPEDITED PROCEDURE – EXAMINING GROUP 2814

S/N 10/612,328

PATENT

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Applicant:	James C Matayabas et al.	Examiner:	Howard Weiss
Serial No.:	10/612,328	Group Art Unit:	2814
Filed:	June 30, 2003	Docket No.:	884.946US1
Title:	POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION		
Assignee:	Intel Corporation	Customer No.:	21186

AMENDMENT & RESPONSE UNDER 37 C.F.R. 1.116

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Final Office Action mailed March 30, 2005, please amend the application as follows: